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ELECTRICAL POTTING COMPOUNDS ADHESION TO TEFLON WIRE AT ELEVATED TEMPERATURES

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MCDONNELL AIRCRAFT CORPORATION

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Additional information pertaining to any data contained herein may be obtained from the Directorate of Materials and Processes (ASRCEM-1), Aeronautical Systems Division, Air Force Systems Command, United States Air Force, Wright-Patterson Air Force Base, Ohio, or McDonnell Aircraft Corporation, St. Louis, Missouri

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SYSTEMS LABORATORY

FINAL REPORT

Electrical Potting Compounds - Adhesion to Terlon Wire at Elevated Temperatures

ABSTRACT

Potted electrical connectors are currently being used at M.A.C. to waterproof MIL-W-16878 Type E Teflon hook-up wire. In order for the hook-up wire to be completely waterproof, the potting compound must adhere to the wires through the temperature range encountered. This test was initiated to compare the adhesion properties of two different silicone potting compounds and two different primers.

RTU-60 and EC-1663 potting compounds and their catalysts, together with EX-B-579-1 and EC-1694 primers were tested under conditions simulating wire bundle installation and removal handling. These tests were conducted before, during and after a 24 hour scak at 500°F.

The major mode of failure was the loss of adhesion of the primer to the Tetra-Etched Teflon hook-up wire.

The EX-B-579-1 primer was superior to the EC-1694 primer. The RTV-60 potting compound appeared to have better adhesion properties than the EC-1663 potting compound.

Tests conducted at 500°F resulted in a considerable loss of adhesion in all cases.

Test Engineer APPROVED BY June 1 June

APPROVED BY () Systems Laboratory

APPROVED BY Laboratory Project Engineer

DISTRIBUTION: C. Fleming, A. Haffner, R. F. Johnson, Eng. Library (abstracts) E. C. McCandlish, C. Fugua, E. Pieper

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1. OBJECTIVE

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To determine the adhesion characteristics of silicone RTV potting compounds relative to MIL-W-16878 Type E Etched Teflon hook-up wire.

2. PROCEDURE

2.1 Test Specimen Preparation

The specimens were prepared as shown in Figure 1, Page 4, and in the quantities shown in Table 1, Page 5, of this report.

The ends of the wires that were embedded in the potting compound were Tetra-Etched in accordance with M.A.C. P.S. 17165 (dated 23 August 1960' and as modified by Ammendment No. 1, dated 31 March 1961).

The potting compound was primed, mixed, applied, and cured as shown in P.S. 17172, Rev. B, dated 9 May 1960, except in the cases where the Hughson Primer was used. In these cases the priming instructions of P.S. 17311, dated 16 November 1960, were followed.

3. TESTING PROCEDURE

Two samples of each type of specimen were tested at each temperature condition described below. ("Type" of specimen includes catalyst variations of GE RTV-60).

- (a) Room temperature
- (b) After 24 hours at 500°F (while still hot)
- (c) Upon cooling to room temperature

The potting-wire adhesion was checked as follows:

While maintaining sufficient tension on the wire to remove all slack, the wire was rotated and oscillated to strain the potting-wire junction and thereby simulate the strains a potted electrical connector endures during wire bundle installation and removal handling. The wire was then tugged sufficiently to fail the potting-wire junction and the relative ease with which failure was obtained and the type of failure (adhesive, cohesive, or both) was noted.

4. TEST RESULTS

The test results are presented in Table 2, Page 6, of this report.

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5. DISCUSSION OF RESULTS

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There appeared to be little difference in specimen preparation or in test results where varied catalysts were used with the RTV-60, though the RTV-9930 catalyst cured the potting compound more rapidly than any of the other RTV catalysts. This catalyst yielded a RTV-60 mix with one hour pot life.

The Teflon wire used in specimens 25 through 32 was a white wire which differed from the wire used in the remaining specimens (a clear coated wire). The white wire, manufactured by the Thermal Wire Co. of America, appeared to give better results than the wire used on the other samples. Both wires were MIL-W-16878 Type E.

Hearly all potting-wire junctions failed relatively easily while tested at condition "b" (while still hot). The failures were nearly all adhesive and appeared to be caused by the failure of the primer to adhere to the Teflon wire.

The EC-169b primer nearly always failed adhesively upon rotation of the wire, even if very little tension was used.

6. CONCLUBION

The major mode of failure was the loss of adhesion of the primer to the Teflon hook-up wire.

The Hughson EX-B579-1 primer was superior to the EC-1694 of the 3M Co.

The best results were obtained using GE RTV-60 potting compound and the RTV-9930 catalyst with the Hughson EX-B579-1 primer.

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	FIGURE 1
	POTTING COMPOUND
	WIRES SPACED SO POTTING IS CLEARLY VISIBLE AROUND EACH ONE
	TETRA-ETCH SHADED AREA
6.0 APPROX.	60 MIN 10
	SMALL ALUMINUM CONTAINER (AMPHENOL 97121-24)

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TABLE 1

SPECIMEN NUMBE	POTTING COMPOUND	CATALYST	CATALYST WEIGHT PEH CENT	PRIMER
1 THRU8	RTV-60	T-12	0.1%	HUGHSON
7 THRU12	RTV-60	T-12	0.1%	EC-1694
13 THRU18	RTV-60	RTV-9910	10%	HUGHSON
19 THRU24	RTV-60	RTV-9910	10%	EC-1094
25THRU30	RTV-60	RTV-9930	10%	HUGHSON
31THRU30	RTV-60	RTV-9930	10%	EC-1694
37THRU42	EC-1663	3M CO.	10%	HUGHSON
43 THRU48	EC-1663	3M CO.	10%	EC-1694

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TABLE 2	DIFFICULT	DIFFICULT	EASY	EASY	DIFFICULT	DIFFICULT	MODERATE	MODERATE	EASY	EASY	EASY	EASY			-RELATIVE	RE	
 -	NONE	NON	EASY	EASY	D. MODERATE DIFFICULT	D. MODERATE	EASY	EASY	EASY	EASY	EASY	EASY				YPE OF FAILURE	TEST
	COHESIVE	COHESIVE	ADHESIVE	ADHESIVE	(c) 80% CO; 20% AD.	(c) 80% CO; 20% AD.	10% CO; 90% AD.	1C% CD; 90% AD.	ADHES IVE	ADHESIVE	10%CO; 90%AD.	10%CO; 90%AD				1X1	CONDITIONS AT
	00	COH	ADF	ADF	30% CC	80% CC	10% CC		ADF	ADF	10%CO;	10%CO					NOU A
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⊢ZO()	DIFFICULT	CIFFICULT	MODERATE	MODERATE	DIFFICULT	DIFFICULT	MOPERATE	MODERATE	ENSY	EASY	EASY	F P S Y			- RELATIVE	FAILURE		
	NONE	NONE	MODERATE	MODERATE	DIFFICULT DIFFICULT	DIFFICULT	EASY	FASY	EASY	EASY	EASY	EASY				- TYPE OF	T TEST	
TABLE	COHESIVE	COMESIVE	ADHESIVE	ADHESIVE	COHESIVE	COHESIVE	10/KO, 90% AD.	10%CO; 90% AD.	ADHESIVE	ADHESIVE	10% CO.; 90% AD.	10% Co.; 90% AD.					CONDITIONS AT TEST	SPECIMEN NUMBER
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TABI	COHESIVE	COHESIUE	50%CO.; 50% AD.	50% CO.; 50% AD.	COHESIVE	COHESIVE	20% CO.; 80% AD	20% CO.; 80% AD.	ADHESIVE	ADHESIVE	10%CO; 90%AD	10%CO.; 90% AD.					CONDITIONS AT TEST	
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100 S	DIFFICULT	DIFFICULT	EASK	FASY	MODERAE	MODERATE	MOLEGATE	MCCERATE	EASY	EASY	MODERATE	MODERATE		RELATIVE	OF FAILURE		
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-	COHESIVE	COMESIUE	(b) 10%(00; 90% AD	(b) 10% (c), 90% AD	70% CO; 30% AD	70%00, 30% AD		10% CO; 90% AD MODERATE	ADHESIVE	ADHESIVE	of AD	50% CO) 50% AD				CONDITIONS	ODDOWN NAMER
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RESISTIVITY AT ELEVATED TEMPERATURES FOR PROTRACTED TIMES

LABORATORY OR DEPT. RESPONSIBLE FOR TEST MODEL 252 Misc. TEST PARTS ON IBM : ON TPL NO. APL/EP PRODUCTION PARTS FOR TEST NOT REQUIRED None

WORK REQUESTED

OBJECTIVE (GIVE PURPOSE OF TEST, WORK AND DATA REQUIRED.

Rev. "A" Revised pages 1, 2 and 3 to cancel all tests concerning the Gore wire and also to check a new 1.0 OBJECT:

catalyst for RTV-60. Mr reduce To determine the adhesion characteristics of silicone RTV potting compounds relative to MIL-W-16878 Type E Teflon hook-up wire, and W. L. Core Type AR Teflon

2.0 HISTORY:

(A)

At present the Teflon hook-up wire being used for Various electrical and electronic purposes is designated as MAC Standard 5M114 Type E. This wire is basically MIL-W-16878 Type E. In another test (TR. 604-001.02) a new mineral-filled Teflon hook-up wire (W. L. Gore Type AR) is being evaluated to determine whether it has properties that would recommend its use instead of the MIL-Spec. wire for certain applications. (TR. 604-001.02 showed the Gore wire not worthy of JUSTIFICATION: further consideration)

To achieve true waterproofing of potted electrical connectors the potting must adhere to the wires. This adhesion must be continuous throughout the temperature range encountered.

4.0 MATERIALS:

- 4.1 G.E. RTV-60 Potting Compound and Catalysts Thermolite-12, and BTW 991 (Supplied by Dopt. 272) RTV-9910, and RTV-9930
- 4.2 3M Co. EO-1663 Potting Compound (from MAC Stock).
- 4.3 Hughson Chemical Co. EX-B579-1 Primer (from MAC Stock).
- 4.4 3M Co. EC-1694 Primer (from MAC Stock).

REFERENCES OR ENCLOSURES

4.0 MATERIALS: (Continued)

4.5 20 gage Teflon Hook-up Wire (5Mll4E20Z9, from MAC Stock).

4.6 20 gage W. L. Co . Type All Tellon Hosh up Wire (201932 PAR, Supplied by Depts 272).

5.0 TEST SPECIMEN PREPARATION:

5.1 The test specimens are to be made as shown in Figure 1 and in the quantities shown in Table I.

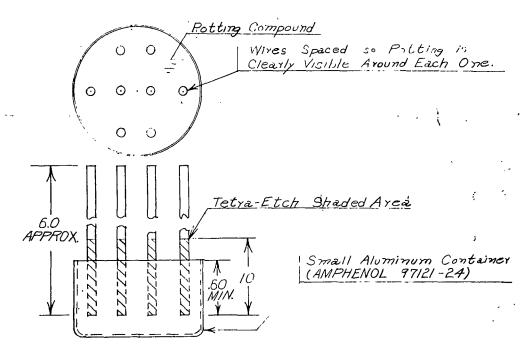


FIGURE 1 - TEST SPECIMEN

- 5.2 The ends of the wires that will be embedded in the potting compound shall be Tetra-Etched in accordance with MAC P.S. 17165 (dated 23 August 1960 and as modified by Amendment No. 1 dated 31 March 1961).
- 5.3 When priming is done with Hughson Primer, follow the PRIMING instructions of P.S. 17311, dated 16 November 1960.
- 5.4 When priming is done with the 3M Co. Primer, follow the PRIMING instructions of P.S. 17172, Rev. B, dated 9 May 1960.
- 5.5 Clean the wires after Tetra-Etching and before priming as shown in P.S. 17172 (NOT as shown in P.S. 17311).
- 5.6 Mix, apply, and cure the potting compound in accordance with P.S. 171.72.

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Q TEST SPECIMEN PREPARATION: (Continued)

5.7 As shown in Table I, use 0.1% by weight of Thermolite-12, 10% by weight of RTV-9910, or 10% by weight of RTV-9930 as the catalyst for the G.E. RTV-60.

Specimen No.	Potting Compound	Catalyst	Primer
1 thru 6	RTV-60	T-12	Hughson
7 thru 12	RTV-60	T-12	EC-1694
13 thru 18	RTV-60	RTV-9910	Hughson
19 thru 24	RTV-60	RTV-9910	EC-1694
25 thru 30	RTV-60	RTV-9930	Hughs on
31 thru 36	RTV-60	RTV-9930	EC-1694
37 thru 42	EC-1663	3M Co.	Hughson
43 thru 48	EC-1663	3M co.	EC-1694

6.0 TESTING PROCEDURE:

- 6.1 Check adhesion of the potting compound to the wires on 2 samples of each type of specimen at each temperature condition described below:
 - (a) Room temperature
 - (b) After 24 hours at 500°F (while still hot).
 - (c) Upon cooling to room temperature.
 - NOTES: (1) "Type" of specimen includes catalyst variations of G.D. RTV-60.
 - (2) Four specimens of a given type are to be placed in a circulating air oven maintained at 500°F for 24 hours.

At the end of this time remove two of the specimens from the oven and allow them to cool completely to room temperature before testing for adhesion. Test the remaining two specimens while in the oven if possible or else immediately upon their removal from the oven before any apprediable cooling occurs.

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6.0 TESTING PROCEDURE: (Continued)

6.1.1 Check potting-wire adhesion as follows:

while maintaining sufficient tension on the wire to remove all slack, rotate and oscillate the wire to strain the potting-wire junction and thereby simulate the strains a potted electrical connector endures during wire bundle installation and removal handling. Tug sufficiently during the rotation and oscillation to fail the potting-wire junction and note whether the failure is adhesive, cohesive, or a combination of the two.

6.2 A representative of Department 272 to be present during these tests.

7.0 DATA REQUIRED:

- 7.1 For each specimen note the type of failure (see paragraph 6.1.1) and the relative ease with which failure was obtained.
- 7.2 Black and white photographs of failure areas.

8.0 SPECIMEN DISPOSITION:

8.1 At the conclusion of the tests return all specimens to Department 272.